



#5/A  
T. Uenky  
5-14-97  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of ) Group Art Unit: 2822  
Shunpei YAMAZAKI et al. )  
Serial No.: 09/118,010 )  
Filed: July 17, 1998 )  
For: SEMICONDUCTOR DEVICE, )  
METHOD OF FABRICATING SAME, )  
AND ELECTROOPTICAL DEVICE )

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on May 3, 1999.

Kriste M. Johnson

AMENDMENT

**RECEIVED**

Assistant Commissioner for Patents  
Washington, D. C. 20231

MAY 13 1999

Sir:

TECHNOLOGY CENTER 2800

In response to the Office Action mailed December 1, 1998, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 9 and 10 without prejudice or disclaimer and amend claims 1 and 5 as follows:

1. (Amended) A semiconductor device comprising:

a [filmy] resinous substrate having an uneven surface;

a resinous layer provided on said uneven surface of said [filmy] resinous substrate and having

a planarized surface; and

A1 Sub C1

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